PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|--------------------|----------------|
| MITSUHIKO MIYAZAKI | 12/19/2022 |

RECEIVING PARTY DATA

| Name: | HAKKO CORPORATION |
|-------------------|-----------------------|
| Street Address: | 4-5, SHIOKUSA 2-CHOME |
| Internal Address: | NANIWA-KU, OSAKA-SHI |
| City: | OSAKA |
| State/Country: | JAPAN |
| Postal Code: | 5560024 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 18115163 |

CORRESPONDENCE DATA

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| ATTORNEY DOCKET NUMBER: | 120180-0334UT01 | |
|-------------------------|-----------------|--|
| NAME OF SUBMITTER: | KATIE KEYS | |
| SIGNATURE: | /Katie Keys/ | |
| DATE SIGNED: | 02/28/2023 | |

Total Attachments: 1

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PATENT 507771967 REEL: 062824 FRAME: 0924

Assignment

Whereas, I/We, Mitsuhiko MIYAZAKI of Osaka, Japan, hereinafter called assignor, have invented certain improvements in HEATER SENSOR COMPLEX AND SOLDERING IRON TIP CARTRIDGE and executed an application for Letters Patent of the United States of America therefor; and

Whereas, HAKKO CORPORATION of 4-5, Shiokusa 2-chome, Naniwa-ku, Osaka-shi, Osaka 5560024 Japan, (assignee), desires to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

I/We, the above named assignor(s), hereby sells, assigns and transfers to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including all divisions, and continuations thereof, and all Letters Patent of the United States that may be granted thereon, and all reissues thereof, and all countries foreign thereto, including rights of priority under the International Convention of Paris (1883) as amended, including the right to claim priority under 35 U.S.C. §119, and I/We request the Director of the U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/We hereby agree that the assignee may apply for foreign Letters Patent on the invention and I/We will execute without further consideration all papers deemed necessary by the assignee in connection with the United States and foreign applications when called upon to do so by the assignee.

s/ Mitsuhiko MIYAZAKI

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. §261)

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RECORDED: 02/28/2023